RENESAS TECHNICAL UPDATE

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Product Category	MPU/MCU	Document No.	TN-RL*-A023A/E	Rev.	1.00	
Title	Correction for Incorrect Description Notice RL78/G10 Descriptions in the Hardware Use Rev. 1.00 Changed	Information Category	Technical Notification			
		Lot No.				
Applicable Product	RL78/G10 R5F10Yxxx	All lots	Reference Document	RL78/G10 User's Manual: Hardware Rev.1.00 R01UH0384EJ0100 (Jun. 2013)		

This document describes misstatements found in the RL78/G10 User's Manual: Hardware Rev.1.00 (R01UH0384EJ0100).

Corrections

Applicable Item	Applicable Page	Contents
Flash ROM: 4 KB of 10-pin products, and 16-pin products	Page 7	Specifications added
3. 1 Address Space	Pages 22 to 24	Incorrect descriptions revised
6. 3. 5 Timer channel enable status register 0 (TE0, TEH0 (8-bit mode))	Page 121	Incorrect descriptions revised
6. 3. 8 Timer output enable register 0 (TOE0)	Page 124	Incorrect descriptions revised
 4. 2 Basic rules of 8-bit timer operation function (only channels 1 and 3) 	Page 132	Specifications added
Figure 10-13. Conversion Operation of A/D Converter	Page 235	Incorrect descriptions revised
10. 9. 3 Conflicting operations	Page 242	Descriptions added
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24. 6. 1 A/D converter characteristics	Page 567	Specifications added
24. 6. 4 Data retention power supply voltage characteristics	Page 568	Descriptions added

Document Improvement

The above corrections will be made for the next revision of the User's Manual: Hardware.



Corrections in the User's Manual: Hardware

No.	Corrections a	nd Applicable Item	IS	Pages in this document
	Document No.	English	R01UH0384EJ0100	for corrections
1	Flash ROM: 4 KB of 10-pin produ products	ucts, and 16-pin	Page 7	Page 3
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10	24. 6. 4 Data retention power su characteristics	oply voltage	Page 568	Page 13

Incorrect: Bold with underline; Correct: Gray hatched

Revision History

RL78/G10 User's Manual: Hardware Rev.1.00 Correction for Incorrect Description Notice

Document Number	Date	Description
TN-RL*-A023A/E	Feb. 6, 2014	First edition issued No.1 to 10 in corrections (This notice)



1. Flash ROM: 4 KB of 10-pin products, and 16-pin products (Page 7)

Flash ROM: 4 KB of 10-pin products and 16-pin products will be added to line-up in the group of RL78/G10. The details of functions of 16-pin products will be made for the next revision of the User's Manual: Hardware.

This outline describes the function at the time when Peripheral I/O redirection register (PIOR) is set to 00H.

Item			10-pin			16-pin				
			R5F10Y14ASP	R5F10Y16ASP	R5F10Y17ASP	R5F10Y44ASP	R5F10Y46ASP	R5F10Y47ASP		
Code flash r	nemory		1 KB	2 KB	4 KB	1 KB	2 KB	4 KB		
RAM	-		128 B	256 B	512 B	128 B	256 B	512 B		
Main system clock	High-spee clock	d system	_			X1, X2 (crystal/ceramic) oscillation, external main system clock input (EXCLK): 1 to 20 MHz: VDD = 2.7 to 5.5 V 1 to 5 MHz: VDD = 2.0 to 5.5 V ^{Note 3}				
	High-spee	d on-chip	• 1.25 to 20	MHz (Vpp = 2.7 to	5.5 V)					
	oscillator o	lock	 1.25 to 5 M 	1Hz (VDD = 2.0 to	5.5 V ^{Note 3})					
Low-speed of	on-chip oscilla	ator clock	15 kHz (TYP)	,	,					
General-pur	pose register		8-bit register ×	8						
Minimum ins	struction exec	ution time	0.05 μs (20 M	Hz operation)						
Instruction s	et		Data transf	fer (8 bits)						
			Adder and	subtractor/logical	operation (8 bits)					
			Multiplicati	on (8 bits \times 8 bits))					
			Rotate, bar	rrel shift, and bit n	nanipulation (set, r	eset, test, and Bo	olean operation), e	etc.		
I/O port	Total		8			14				
	CMOS I/O		6 (N-ch open-	6 (N-ch open-drain output (VDD tolerance): 2) 10 (N-ch open-drain output (VD				(VDD tolerance): 4)		
	CMOS inp	ut	2	2 4						
Timer	16-bit time	r	2 channels			4 channels				
	Watchdog	timer	1 channel	channel						
	12-bit inter	val timer	— 1 channel							
	Timer outp	out	2 channels (PWM output: 1) 4 channels (PWM outputs: 3 ^{Note 1}))		
Clock output	t/buzzer outp	ut	1							
			2.44 kHz to 10 MHz: (Peripheral hardware clock: fmain = 20 MHz operation)							
Comparator			—			1				
8-/10-bit res	olution A/D c	onverter	4 channels	4 channels 7 channels						
Serial interfa	ice		[10-pin produc	ts] CSI: 1 channe	el/simplified l ² C: 1	channel/UART: 1 o	channel			
		.2	[16-pin produc	ts] CSI: 2 channe	els/simplified I ² C: 1	channel/UART: 1	channel			
		I ² C bus	—			1 channel				
Vectored inters	errupt	Internal	8			14				
Key internue	4	External	3			5				
Rey Interrup	t		0							
Reset		 Reset by RESET pill Internal reset by watchdog timer Internal reset by selectable power-on-reset Internal reset by illegal instruction execution ^{Note 2} Internal reset by data retention lower limit voltage 								
Selectable p	ower-on-rese	et circuit	 Detection voltage Rising edge (Vspor): 2.25 V/2.68 V/3.02 V/4.45 V (max.) Falling edge (Vspbr): 2.20 V/2.62 V/2.96 V/4.37 V (max.) 							
On-chip deb	ug function		Provided							
Power suppl	y voltage		VDD = 2.0 to 5	.5 V Note 3						
Operating a	mbient tempe	erature	TA = - 40 to + 85 °C							

Notes 1. The number of outputs varies, depending on the setting of channels in use and the number of the master (see6.9.4 Operation as multiple PWM output function).

- 2. The illegal instruction is generated when instruction code FFH is executed. Reset by the illegal instruction execution not issued by emulation with the on-chip debug emulator.
- **3.** Use this product within the voltage range from 2.25 to 5.5 V because the detection voltage (V_{SPOR}) of the selectable power-on-reset (SPOR) circuit should also be considered.



Correct:

2. <u>3. 1 Address Space (Pages 22 to 24)</u>

Incorrect:

Figure 3-1. Memory Map for the R5F10Y14ASP and R5F10Y44ASP



Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.

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Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.

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Date: Feb. 6,2014

Incorrect:

Figure 3-2. Memory Map for the R5F10Y16ASP and R5F10Y46ASP



Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.



Correct:

FFFFFH

FFF00H



Special function register (SFR)

256 bytes



Figure 3-2. Memory Map for the R5F10Y16ASP and R5F10Y46ASP

007FFH

Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.



Incorrect:

Figure 3-3. Memory Map for the R5F10Y47ASP



Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.

Date: Feb. 6,2014

Correct:

Figure 3-3. Memory Map for the R5F10Y17ASP and R5F10Y47ASP

00FFFH FFFFFH Special function register (SFR) 256 bytes FFF00H FFEFFH General-purpose register 8 bytes FFEF8H FFEF7H Reserved FFEE0H FFEDFH RAM 512 bytes FFCE0H FFCDFH Program area Reserved F9000H F8FFFH Mirror 4KB F8000H F7FFFH Reserved F0800H 000CEH F07FFH 000CDH Special function register (2nd SFR) On-chip debug Note F0000H 2KB security ID setting area EFFFFH 000C4H 10 bytes 000C3H Option byte area Note 000C0H 4 bytes 000BFH Reserved CALLT table area 64 bytes 00080H 0007FH Vector table area 00FFFH 128 bytes Code flash memory 4KB 00000H 00000H

Note Set the option bytes to 000C0H to 000C3H, and the on-chip debug security IDs to 000C4H to 000CDH.

Caution Access to the reserved area is prohibited.



3. <u>6. 3. 5 Timer channel enable status register 0 (TE0, TEH0 (8-bit mode))</u> (Page 121)

Incorrect:

The TE0 and TEH0 registers are used to enable or stop the timer operation of each channel.

Each bit of the TE0 and TEH0 registers correspond to each bit of the timer channel start register 0 (TS0, TSH0) and the timer channel stop register 0 (TT0, TTH0). When a bit of the TS0 and TSH0 registers is set to 1, the corresponding bit of TE0 and TEH0 is set to 1. When a bit of the TT0 and TTH0 registers is set to 1, the corresponding bit of TE0 and TEH0 is cleared to 0.

The TE0 and TEH0 registers can be read by an 8-bit memory manipulation instruction.

Reset signal generation clears TE0 and TEH0 registers to 00H.

4. 6. 3. 8 Timer output enable register 0 (TOE0) (Page 124)

Incorrect:

The TOE0 register is used to enable or disable timer output of each channel.

Channel n for which timer output has been enabled becomes unable to rewrite the value of the TO0n bit of timer output register 0 (TO0) described later by software, and the value reflecting the setting of the timer output function through the count operation is output from the timer output pin (TO0n).

The TOE0 register can be set by an 8-bit memory manipulation instruction. Reset signal generation clears this register to 00H.

5. <u>6. 4. 2 Basic rules of 8-bit timer operation function</u> (only channels 1 and 3) (Page 132)

Old:

The 8-bit timer operation function makes it possible to use a 16-bit timer channel in a configuration consisting of two 8-bit timer channels.

This function can only be used for channels 1 and 3, and there are several rules for using it. The basic rules for this function are as follows:

(omitted)

(7) The lower 8 bits operate according to the settings of TMR0nH and TMR0nL registers. The following four functions support operation of the lower 8 bits:

- Interval timer function
- External event counter function
- · Delay count function
- PWM output

Correct:

The TEO and TEHO registers are used to enable or stop the timer operation of each channel.

Each bit of the TE0 and TEH0 registers correspond to each bit of the timer channel start register 0 (TS0, TSH0) and the timer channel stop register 0 (TT0, TTH0). When a bit of the TS0 and TSH0 registers is set to 1, the corresponding bit of TE0 and TEH0 is set to 1. When a bit of the TT0 and TTH0 registers is set to 1, the corresponding bit of TE0 and TEH0 is cleared to 0.

The TE0 and TEH0 registers can be read by a 1-bit or 8-bit memory manipulation instruction.

Reset signal generation clears TE0 and TEH0 registers to 00H.

Correct:

The TOE0 register is used to enable or disable timer output of each channel.

Channel n for which timer output has been enabled becomes unable to rewrite the value of the TOOn bit of timer output register 0 (TOO) described later by software, and the value reflecting the setting of the timer output function through the count operation is output from the timer output pin (TOOn).

The TOE0 register can be set by a 1-bit or 8-bit memory manipulation instruction. Reset signal generation clears this register to 00H.

New:

The 8-bit timer operation function makes it possible to use a 16-bit timer channel in a configuration consisting of two 8-bit timer channels.

This function can only be used for channels 1 and 3, and there are several rules for using it. The basic rules for this function are as follows:

(omitted)

(7) The lower 8 bits operate according to the settings of TMR0nH and TMR0nL registers. The lower 8-bit timer supports the following functions:

- Interval timer
- Square wave output
- External event counter
- Delay counter
- PWM output function
- Multiple PWM output function (16-pin products only)



6. Figure 10-13. Conversion Operation of A/D Converter (Page 235)







A/D conversion is performed once when the bit 7 (ADCS) of the A/D converter mode register 0 (ADM0) is set to 1 by software.

Reset signal generation clears the A/D conversion result register (ADCRL, ADCRH) to 00H.

Date: Feb. 6,2014

Correct:





A/D conversion is performed once when the bit 7 (ADCS) of the A/D converter mode register 0 (ADM0) is set to 1 by software. The ADCS bit is automatically cleared to 0 after A/D conversion ends.

Reset signal generation clears the A/D conversion result register (ADCRH, ADCRL) to 00H.



7. 10. 9. 3 Conflicting operations (Page 242)

Old:

10.9.3 Conflicting operations

Writing to the ADM0 register has priority if conflict between writing to the ADCRH or ADCRL register and writing 0 to the A/D converter mode register 0 (ADM0) occurs at the end of conversion. Writing to the ADCRH or ADCRL register is not performed, nor is the conversion end interrupt signal (INTAD) generated.

New:

10.9.3 Conflicting operations

- <1> Reading from the ADCRH or ADCRL register has priority if conflict between writing to the A/D conversion result register (ADCRH, ADCRL) and reading from ADCRH or ADCRL register by software operation occurs at the end of conversion. After the read operation, the new conversion result is written to the ADCRH or ADCRH register.
- <2> Writing to the ADM0 register has priority if conflict between writing to the ADCRH or ADCRL register and writing to the A/D converter mode register 0 (ADM0) occurs at the end of conversion. Writing to the ADCRH or ADCRL register is not performed, nor is the A/D conversion end interrupt signal (INTAD) generated.



8. 24. 3. 1 Pin characteristics (Page 556)

This shows the specifications changed in the ELECTRICAL SPECIFICATIONS of 10-pin products. The ELECTRICAL SPECIFICATIONS of "Flash ROM: 4 KB of 10-pin products and 16-pin products" will be made for the next revision of the User's Manual: Hardware.

Old:

24.3.1 Pin characteristics

$(T_A = -40 \text{ to } +85^{\circ}\text{C}, 2.0 \text{ V} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{V}_{\text{SS}} = 0 \text{ V})$

Parameter	Symbol	Conditions MIN.					MAX.	Unit
Output current,	Іон1	P00, P01, P02 to P04, P40	Per pin				-10.0 Note 2	mA
high		P40	Total ^{Note 3}	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-10.0	mA
				$2.7~V \leq V_{\text{DD}} < 4.0~V$			-2.0	mA
				$2.0~V \leq V_{\text{DD}} < 2.7~V$			-1.5	mA
		P00, P01,	Total ^{Note 3}	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-50.0	mA
		P02 to P04		$2.7~V \leq V_{\text{DD}} < 4.0~V$			-10.0	mA
				$2.0~V \leq V_{\text{DD}} < 2.7~V$			-7.5	mA
		Total of all pins ^{Note}	3				-60.0	mA
Output current,	Iol1	P00 to P04, P40	Per pin				20.0 Note 2	mA
low		P40	Total ^{Note 3}	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			20.0	mA
				$2.7~V \leq V_{\text{DD}} < 4.0~V$			3.0	mA
				$2.0~V \leq V_{\text{DD}} < 2.7~V$			0.6	mA
		P00 to P04	Total ^{Note 3}	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			80.0	mA
				$2.7~V \leq V_{\text{DD}} < 4.0~V$			12.0	mA
				$2.0~V \leq V_{\text{DD}} < 2.7~V$			2.4	mA
		Total of all pins ^{Note}	3				100.0	mA

(omitted)

New:

24.3.1 Pin characteristics

$(T_A = -40 \text{ to } +85^{\circ}C, 2.0 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{ Vss} = 0 \text{ V})$

Parameter	Symbol	Condition	s	MIN.	TYP.	MAX.	Unit
Output Іонı current, high ^{Note 1}	Per pin for 10-pin products: P00 to P04, F 16-pin products: P00 to P07, F	P40 P40, P41			-10.0 Note 2	mA	
	Total of 10-pin products: P40 16-pin products: P40, P41 (When duty ≤ 70% ^{Note 3})	$\begin{array}{l} 4.0 \ V \leq V_{DD} \leq 5.5 \ V \\ \hline 2.7 \ V \leq V_{DD} < 4.0 \ V \\ \hline 2.0 \ V \leq V_{DD} < 2.7 \ V \end{array}$			-20.0 -4.0 -3.0	mA mA mA	
	Total of 10-pin products: P00 to P04 16-pin products: P00 to P07 (When duty \leq 70% ^{Note 3})	$\begin{array}{l} 4.0 \ V \leq V_{DD} \leq 5.5 \ V \\ \hline 2.7 \ V \leq V_{DD} < 4.0 \ V \\ \hline 2.0 \ V \leq V_{DD} < 2.7 \ V \end{array}$			-60.0 -12.0 -9.0	mA mA mA	
Tc Output IoL1 Percent current, 10 low Note 4 16 Tc 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10	Total of all pins (When duty ≤ Per pin for 10-pin products: P00 to P04, F 16-pin products: P00 to P07, F	240 240, P41			-80.0 20.0 Note 2	mA mA	
	Total of 10-pin products: P40 16-pin products: P40, P41 (When duty ≤ 70% ^{Note 3})	$\begin{array}{l} 4.0 \ V \leq V_{DD} \leq 5.5 \ V \\ \\ 2.7 \ V \leq V_{DD} < 4.0 \ V \\ \\ 2.0 \ V \leq V_{DD} < 2.7 \ V \end{array}$			40.0 6.0 1.2	mA mA mA	
		Total of 10-pin products: P00 to P04 16-pin products: P00 to P07 (When duty \leq 70% ^{Note 3})	$\begin{array}{l} 4.0 \ V \leq V_{DD} \leq 5.5 \ V \\ \hline 2.7 \ V \leq V_{DD} < 4.0 \ V \\ \hline 2.0 \ V \leq V_{DD} < 2.7 \ V \end{array}$			80.0 12.0 2.4	mA mA mA
		Total of all pins (When duty \leq	70% ^{Note 3})			120.0	mA

(omitted)



9. 24. 6. 1 A/D converter characteristics (Page 567)

This shows the specifications changed in the ELECTRICAL SPECIFICATIONS of 10-pin products. The ELECTRICAL SPECIFICATIONS of "Flash ROM: 4 KB of 10-pin products and 16-pin products" will be made for the next revision of the User's Manual: Hardware.

Old:

24.6.1 A/D converter characteristics

(Target ANI pin : ANI0 to ANI3)

(TA = -40 to +85°C, 2.4 V \leq VDD \leq 5.5 V, Vss = 0 V)

Parameter	Symbol	(Conditions	MIN.	TYP.	MAX.	Unit
Resolution	Res			8		10	bit
Overall error ^{Note.1}	AINL	10-bit	V _{DD} = 5 V		±1.7	±3.1 Note 2	LSB
		resolution	V _{DD} = 3 V		±2.3	±4.5 ^{.Note.2}	LSB
Conversion time	t CONV	10-bit	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	3.4		18.4	μs
		resolution	$2.4~V \leq V_{\text{DD}} \leq 5.5~V$	4.6		18.4	μs
Zero-scale	Ezs	10-bit	10-bit V _{DD} = 5 V			$\pm 0.19^{\text{Note.2}}$	%FSR
error ^{Note 1}		resolution	V _{DD} = 3 V			±0.39 ^{.Note.2}	%FSR
Full-scale	Ers	10-bit	V _{DD} = 5 V			±0.29 ^{.Note.2}	%FSR
error ^{Note 1}		resolution	V _{DD} = 3 V			± 0.42 Note 2	%FSR
Integral linearity	ILE	10-bit	V _{DD} = 5 V			±1.8 ^{Note 2}	LSB
error ^{Note 1}		resolution	V _{DD} = 3 V			±1.7 ^{Note 2}	LSB
Differential	DLE	10-bit	V _{DD} = 5 V			±1.4 ^{.Note.2}	LSB
linearity error ^{Note.1}		resolution	V _{DD} = 3 V			±1.5 ^{.Note.2}	LSB
Analog input voltage	Vain			0		Vdd	V

Notes 1. Excludes quantization error (±1/2 LSB).

2. This is the characteristic evaluation value plus or minus 3. These values are not used in the shipping inspection.

New:

24.6.1 A/D converter characteristics

(Target pin: ANI0 to ANI6, internal reference voltage)

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 2.4 \text{ V} \le \text{V}_{\text{DD}} \le 5.5 \text{ V}, \text{V}_{\text{SS}} = 0 \text{ V})$

Parameter	Symbol	Co	MIN.	TYP.	MAX.	Unit	
Resolution	RES			8		10	bit
Overall error	AINL	10-bit	V _{DD} = 5 V		±1.7	±3.1	LSB
Notes 1, 2, 3		resolution	V _{DD} = 3 V		±2.3	±4.5	LSB
Conversion time	tconv	10-bit	$2.7~V \leq V_{\text{DD}} \leq 5.5~V$	3.4		18.4	μs
		resolution Target pin: ANI0 to ANI6	$\begin{array}{l} 2.4 \ V \leq V_{\text{DD}} \leq 5.5 \ V \\ \hline \text{Note 5} \end{array}$	4.6		18.4	μs
		10-bit resolution Target pin: internal reference voltage ^{Note 6}	$2.4~V \leq V_{DD} \leq 5.5~V$	4.6		18.4	μs
Zero-scale	Ezs	10-bit	V _{DD} = 5 V			±0.19	%FSR
error ^{Notes 1, 2, 3, 4}		resolution	V _{DD} = 3 V			±0.39	%FSR
Full-scale error	Efs	10-bit	V _{DD} = 5 V			±0.29	%FSR
Notes 1, 2, 3, 4		resolution	V _{DD} = 3 V			±0.42	%FSR
Integral linearity	ILE	10-bit	V _{DD} = 5 V			±1.8	LSB
error ^{Notes 1, 2, 3}		resolution	V _{DD} = 3 V			±1.7	LSB
Differential linearity	DLE	10-bit	V _{DD} = 5 V			±1.4	LSB
error ^{Notes 1, 2, 3}		resolution	V _{DD} = 3 V			±1.5	LSB
Analog input	VAIN	Target pin: ANIC) to ANI6	0		Vdd	V
voltage		Target pin: inter	nal reference voltage		/REG Note 7		V

(Notes are listed on the next page.)



Notes 1. TYP. Value is the average value at T _A = 25°C. MAX. value is the average value $\pm 3\sigma$
at normal distribution.
2. These values are the results of characteristic evaluation and are not checked for
shipment.
3. Excludes quantization error ($\pm 1/2$ LSB).
4. This value is indicated as a ratio (%FSR) to the full-scale value.
5. Set the LV0 bit in the A/D converter mode register 0 (ADM0) to 0 when conversion
is done in the operating voltage range of 2.4 V \leq V _{DD} $<$ 2.7 V.
6. Set the LV0 bit in the A/D converter mode register 0 (ADM0) to 0 when the internal
reference voltage is selected as the target for conversion.
7. Refer to 24.6.3 Internal reference voltage characteristics.
Cautions 1. Arrange wiring and insert the capacitor so that no noise appears on the
power supply/ground line.
2. Do not allow any pulses that rapidly change such as digital signals to
be input/output to/from the pins adjacent to the conversion pin during
A/D conversion.
3. Note that the internal reference voltage cannot be used as the
reference voltage of the comparator when the internal reference
voltage is selected as the target for A/D conversion.



10. 24. 6. 4 Data retention power supply voltage characteristics (Page 568)

This shows the specifications changed in the ELECTRICAL SPECIFICATIONS of 10-pin products. The ELECTRICAL SPECIFICATIONS of "Flash ROM: 4 KB of 10-pin products and 16-pin products" will be made for the next revision of the User's Manual: Hardware.

Old:

24.6.4 Data retention power supply voltage characteristics

$(T_A = -40 \text{ to } +85^{\circ}\text{C}, \text{Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention power	VDDDR		1.9		5.5	V
supply voltage range						

Caution Data is retained until the power supply voltage becomes under the minimum value of the data retention power supply voltage range. Note that data in the RAM and RESE registers might not be cleared even if the power supply voltage becomes under the minimum value of the data retention power supply voltage range.

New:

24.6.6 Data retention power supply voltage characteristics

$(T_A = -40 \text{ to } +85^{\circ}\text{C}, \text{Vss} = 0 \text{ V})$

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Data retention power	VDDDR		1.9		5.5	V
supply voltage						

Caution Data in the RESF register is retained until the power supply voltage becomes under the minimum value of the data retention power supply voltage (VDDDR). Note that data in the RESF register might not be cleared even if the power supply voltage becomes under the minimum value of the data retention power supply voltage (VDDDR).



